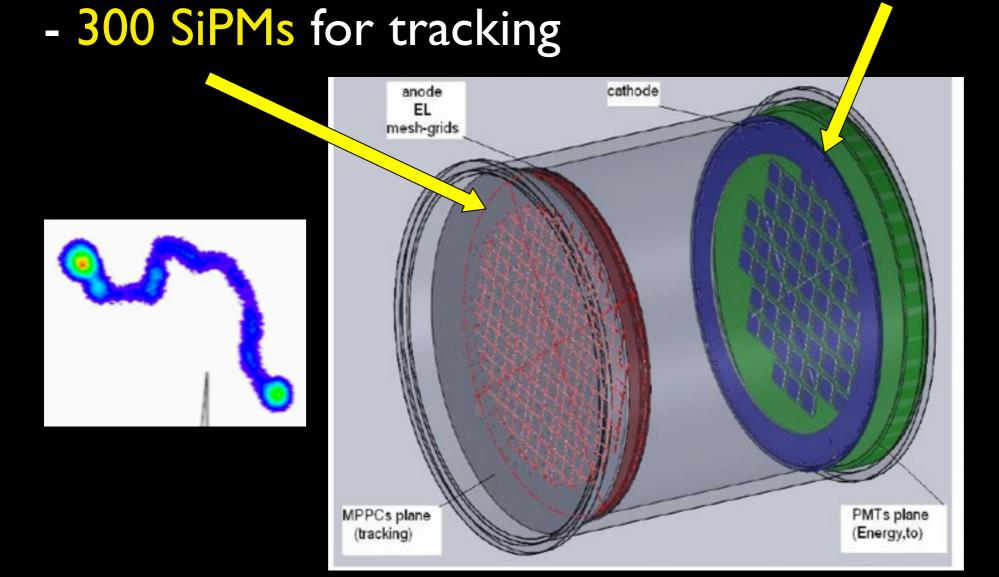
# An SRS DAQ for NEXT-I-EL

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RD51 meeting - Bari, October 2010

### NEXT-I-EL

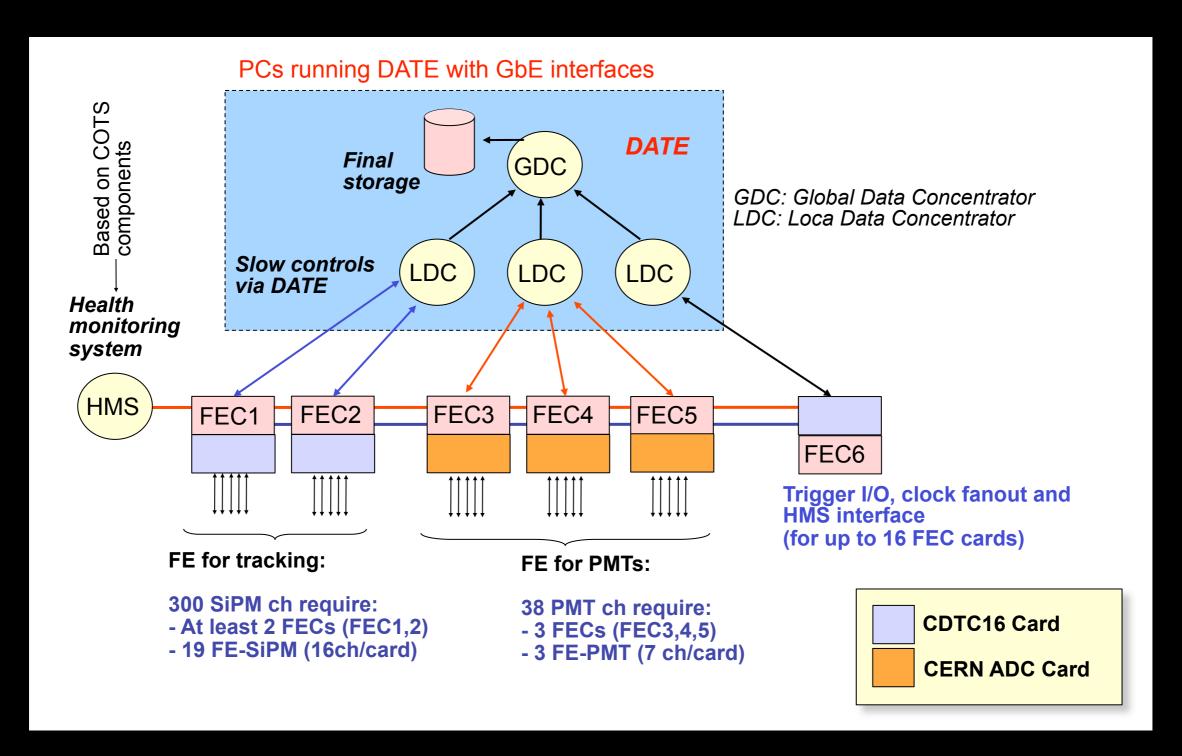
- NEXT is a bb-0n experiment based on a Gas XeTPC
- NEXTI-EL is a small electroluminiscent TPC prototype:
  - t0 and energy are measured by 19 PMTs



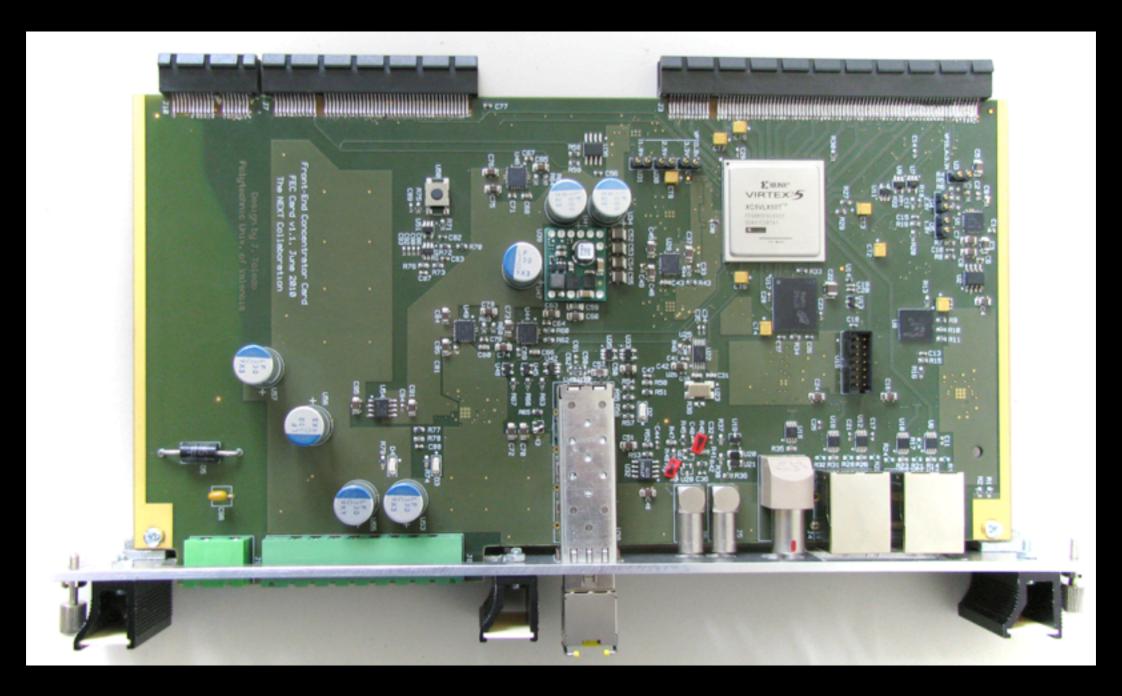
### NEXT-I-EL

- PMT FE: dual path per channel (E, t0) amp + shaper
  - 19 + 19 analog outputs
  - 3 CERNADC C-cards needed to digitize all 38 ch
  - 3 FECs needed
- SiPM FE: amp + gated integrator + digitizer + LVDS ouput
  - Digital outputs (RJ45 conn., 4 LVDS pairs)
  - 16ch/ FE board, so we need 20 FE boards
  - Interface to DAQ: either SRU of FEC + LVDS interface
  - I SRU or 2 FECs needed
- NEXT-I-EL will be operational by Dec.2010, so a small batch of FEC vI.2 is undergoing right now

# NEXT-I-EL DAQ architecture

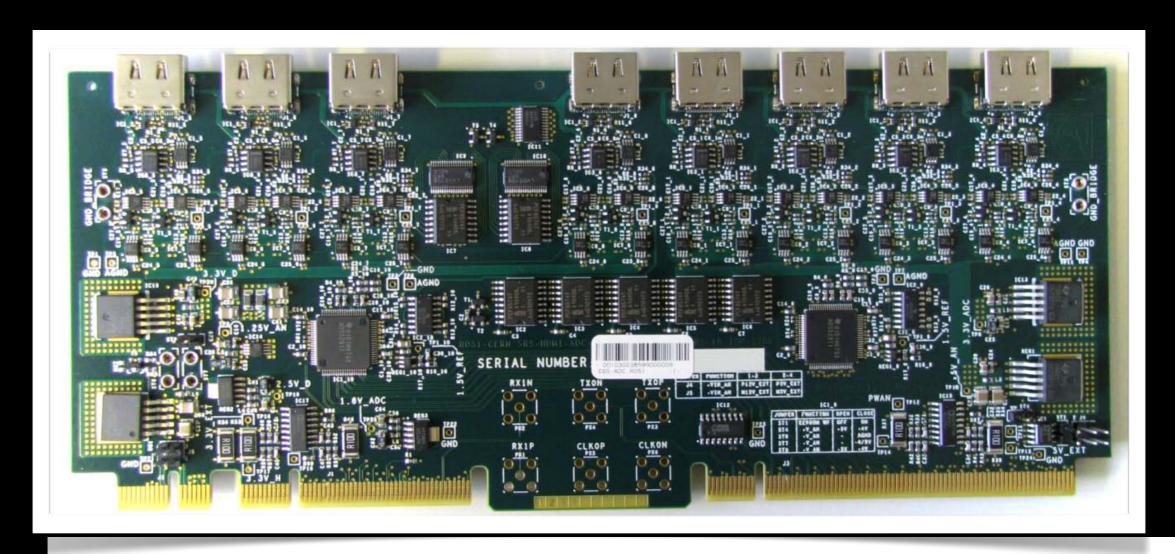


# DAQ components



I - The FEC card (6 units)

# DAQ components

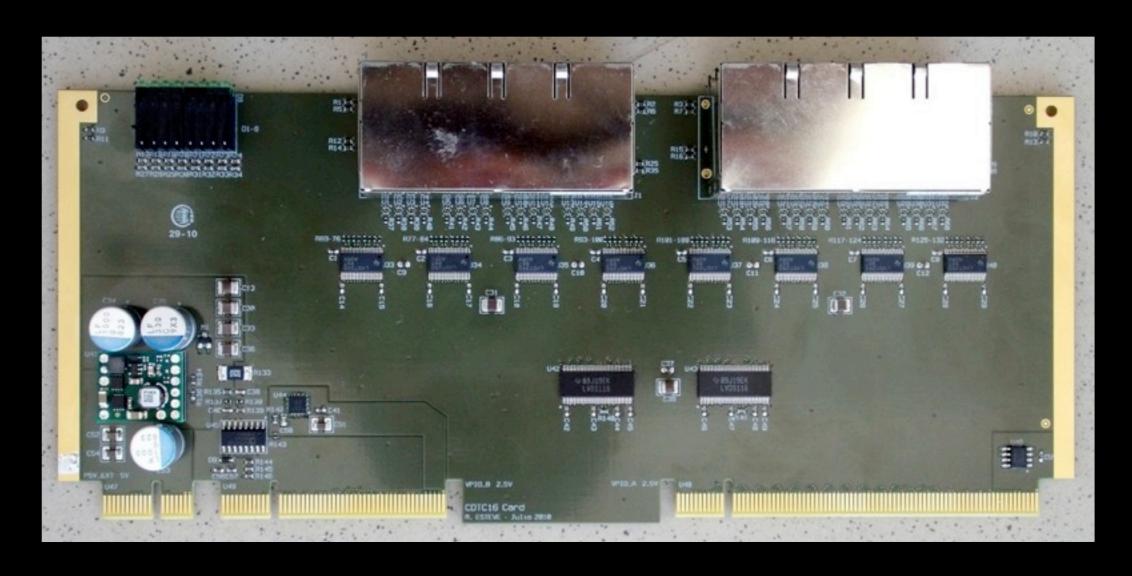


#### ADC C-Card Overview



2 Octal ADCs with LVDS serial

## DAQ components



III - The CDTC16: a 16x LVDS RJ45 interface C-card. Used as tracking (2 units) and trigger interface (1 unit).

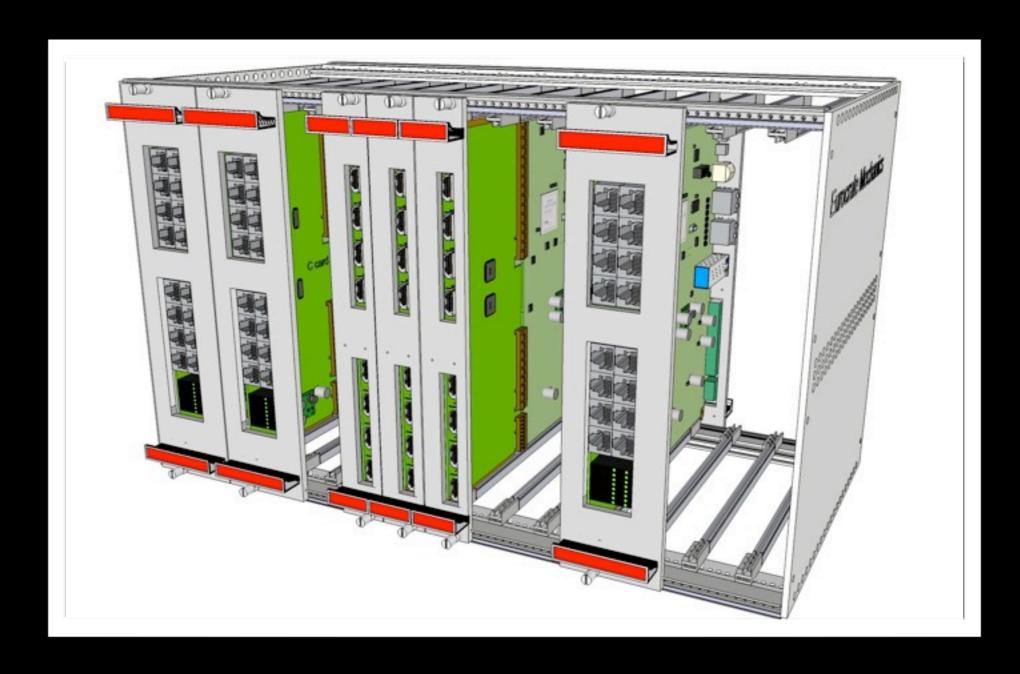
## The CDTC 16 card



- NEXT design, approx. 600 €
- 16 x RJ45 conns., 4 x LVDS each
- 2 LVDS in, 2 LVDS out per connector
- Common Trig and clock+command outputs
- 200/400 Mb/s data inputs from each RJ45
- Dual use as FE-SiPM interface and Trigger board

16 channel Clock, Data, Trigger and Control

## The NEXT-I-EL DAQ box



6x FECs: 3 x ADC + 3 x LVDS interface

# Coming milestones

- Oct.2010: new FECv1.2 production starts urgently
- Dec.2010: the complete DAQ must be ready to operate
- Jan.-June 2011: DAQ test and operation, <u>a lot of FW</u> design !!
- June-Dec. 2011: Looking towards NEXT-100: cost reduction, new technologies evaluation: SRU as DAQ backbone. NEXT-100 has approx. 10k SiPM ch + 400 PMTs

## Thanks for your attention